

# Hanwha

## Ethylene Vinyl Acetate copolymer

# EVA 2518

Foam Molding Grade

**MELT INDEX** 2.5

**VA CONTENT** 18.2

Hanwha EVA 2518 is manufactured by IPC, an affiliate of Hanwha in The Kingdom of Saudi Arabia using an Exxon-Mobil high pressure tubular process and designed for variety of foam molding application such as shoes and sandals etc.. EVA 2518 is well known for its excellent processability and high quality assurance.

### ■ Outstanding Properties

Excellent Foam Molding Property  
Very Good Mechanical Properties  
Excellent Loading Property of Various Fillers  
Good Elastic Property of Sponge

### ■ Additives

Anti-Oxidant

### ■ Physical Properties

Physical Properties	Unit	Test Method	Value
Melt Index	g/10min	ASTM D1238	2.5
VA Content	wt%	IPC Method	18.2
Density	g/cm <sup>3</sup>	IPC Method	0.935
Vicat Softening Point	°C	ASTM D1525	64
Melting Point	°C	IPC Method	87
Tensile Strength at Yield	MPa	ASTM D638	5.2
Tensile Strength at Break	MPa	ASTM D638	11
Elongation at Yield	%	ASTM D638	260
Elongation at Break	%	ASTM D638	>800
Flexural Modulus	MPa	ASTM D790	60
Hardness	Shore A/D	ASTM D2240	76/36

<sup>1</sup> These are typical values, not specifications. Some of the physical property values depend on the test equipment geometry and test conditions.



Hanwha Chemical Malaysia Sdn. Bhd., Level 22, Menara Citibank, 165 Jalan Ampang, 50450 Kuala Lumpur, Malaysia.

Tel: +60-3-2161-8001 Fax: +60-3-2163-6001

*The preliminary information in this document is provided for pre-marketing purposes only, and relates only to the named product or materials when not in combination with any other product or materials. The information and recommendations presented herein are to the best of our knowledge true and accurate, but no warranty or guarantee, expressed or implied, is made. Before using one of the products mentioned herein, customers and other users should take care in determining the suitability of such product for the intended use. Hanwha Chemical and International Polymers Company do not accept any liability whatsoever arising from the use of this information or the use, application or processing of any product described herein.*